A growing number of IC designs are utilizing Gel type encapsulation compounds. Whether it is for diaphragms on the die for pressure detection, less stress on newer thinner dies, or extreme temperature variations faced by the automotive industry, this type of compound seems impervious to chemical, plasma, or even laser decapsulation.

*Until now!* - Our FA-LIT Gel Decapsulation Process now safely removes Gel compound “All the way down to the die” in seconds. Without harsh chemicals, the FA-LIT provides a Green solution.